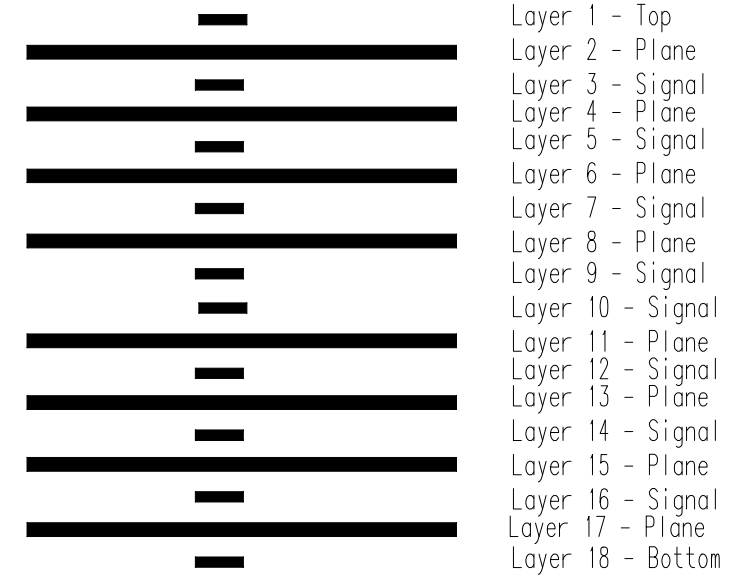


Stackup - 18 Layer Board



Notes:

1. Material - Magtron 6
2. Electroless Nickel/Immersion Gold Plating; min 25umCu, 2.5-5um Ni, 0.05-0.2um Au
3. Vias in pad must be filled with solid fills, planarized and plated over.
4. 1 Oz Cu on Top, Bottom, and internal Planes, 0.50z Cu on internal Signal Layers
5. Controlled Impedance: 580hm - single ended, 990hm - Differential
6. Board Thickness: 0.095" +/- 10%
7. Minimum Trace Width/Clearance: 4mils
- 8 Remove all nonfunctional inner layer pads for pins and vias
9. 45 Degree Chamfer
10. Mill 2.5mm on two edges of the board, on bottom side only, to a remaining thickness of 0.07" +/-10%

Specifications Drawing

PCB # 3004-Rev B - 500MHz ADC Board

6/7/2023